

Signal Integrity Cheat Sheet - Data-Rate Driven Design Decisions

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Date: October 5, 2022

Track: SI

EDI CON

ONLINE



Donald Telian is a Signal Integrity Consultant and owner of SiGuys. He celebrates four decades of SI pioneering with the publication of his new book “**Signal Integrity, In Practice.**” Consulting since the beginning of the serial link revolution, he consistently helps customers migrate to next-generation data rates again and again. With tens of thousands of serial links in production spanning all types of electronic standards and products, he simplifies SI by sharing what’s necessary and what isn’t. Donald is widely known as the SI designer of the **PCI** bus and the originator of **IBIS** modeling and has taught SI techniques to thousands of engineers in more than 15 countries. His book “Signal Integrity, In Practice” brings fresh articulation to the practice of SI for the decades ahead.

Signal Integrity has

CHANGED

(we might even say: simplified)

Why do I say that?

- Signal Integrity no longer used for PCB-level timing closure
 - Serial links embed timing within signals
- DDRx SI handled with proven cut-and-paste layout examples
- Rx (and Tx) equalization increasingly powerful
 - Much of SI is now handled inside the chip, little/no signal seen on PCB
- Decreasing industry demand for SI training (staff?)
 - Comes in waves, next one is approaching
- SI skills deployed for “out-of-the-box” implementation

Nevertheless, there's some basic things to know. Ready?

Signal Integrity Cheat Sheet



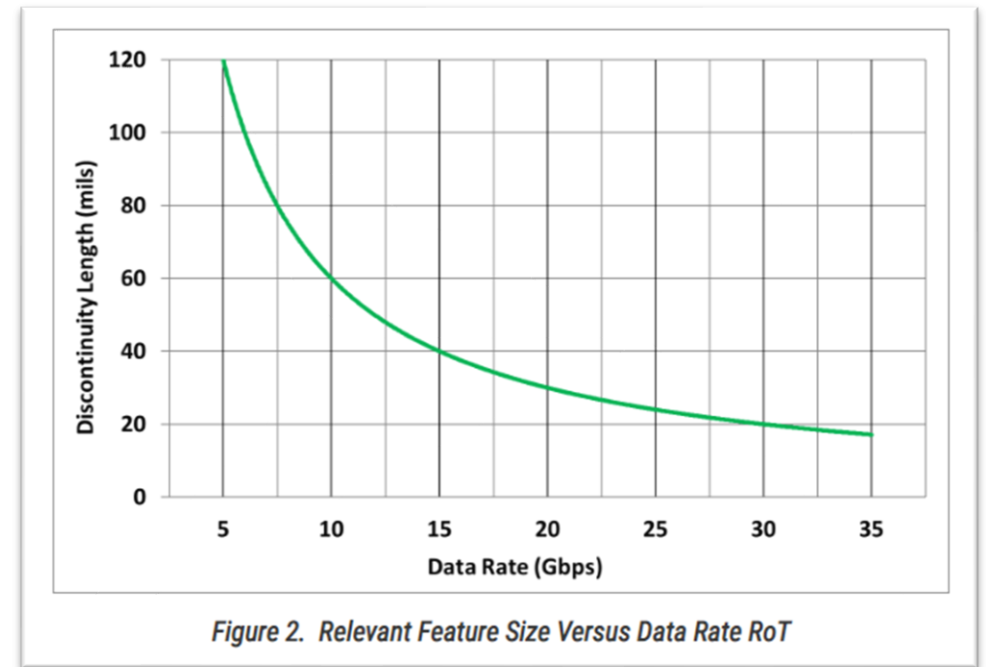
Feature	4 Gbps	8 Gbps	16 Gbps	32 Gbps	Unit	SIIP Section	
Industry/PCIe terminology	Gen2	Gen3	Gen4	Gen5			
Fundamental Frequency	2	4	8	16	GHz		
Relevant Feature Size	160	80	40	20	mils	4.1, 2.1, 4.x	
what's that?	traces	vias	conn pads	everything		4.2, 4.3, 4.4	
Max Stub	64	32	16	8	mils	2.5, 1.3.3	
backdrills	none?	seq-lam	2 layers	per-layer			
P/N Matching, static	10	5	2	1	mils	2.3	
P/N Matching, dynamic			10 in 1.5"	5 in 1"	mils	2.3, 2.4	
Route Style	45°	45°	curved	curved		2.4	
Diff-pair Spacing (XY/Z, min)	25	25	25	30	mils	5.3	
Insertion Loss (max)	16	22	28	36	dB	2.2, 3.5	
Min EQ: Tx_FFE/Rx_DFE taps, CTLE	1 / 0	2 / 1, C	2 / 2, C	2 / 3, C	#taps	3.3, 3.4, 2.7	
Length match method	serpentes		irregular spaced bumps			2.4	
Fiberglass weave	spread glass and rotate image 12 degrees on panel					2.6	
GND Return Vias (GRVs)	within 30 mils of signal layer transition (see DesCon 2022)						Figure 17
Solid GND reference layers	both sides of trace (don't use microstrips)					2.3, 2.6	

To avoid crosstalk

↑ that's my new book

Relevant Feature Size (RFS)

- What is the smallest structure a signal will “see” at a given data rate
 - As such, need to solve/match impedance to prevent reflection (noise)
- $RFS = 0.6 * UI \text{ mils}$ (UI in ps)
 - Based on edge-rate/round-trip
- Details at [Signal Integrity Journal](#)



Signal Integrity Journal
Signal Integrity · Power Integrity · EMC/EMI

Which Discontinuities are Small Enough to Ignore?

April 1, 2022 Donald Telian No Comments

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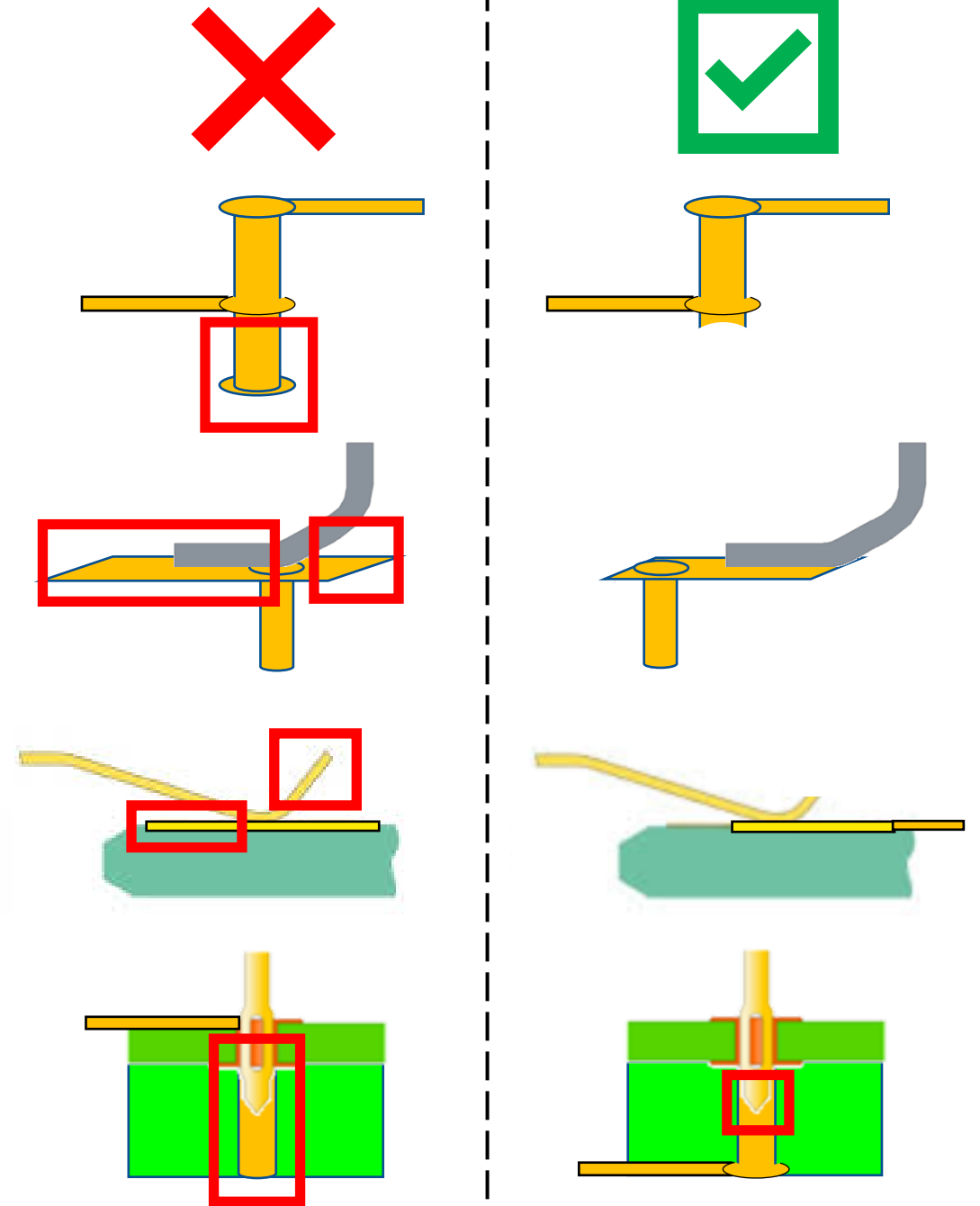
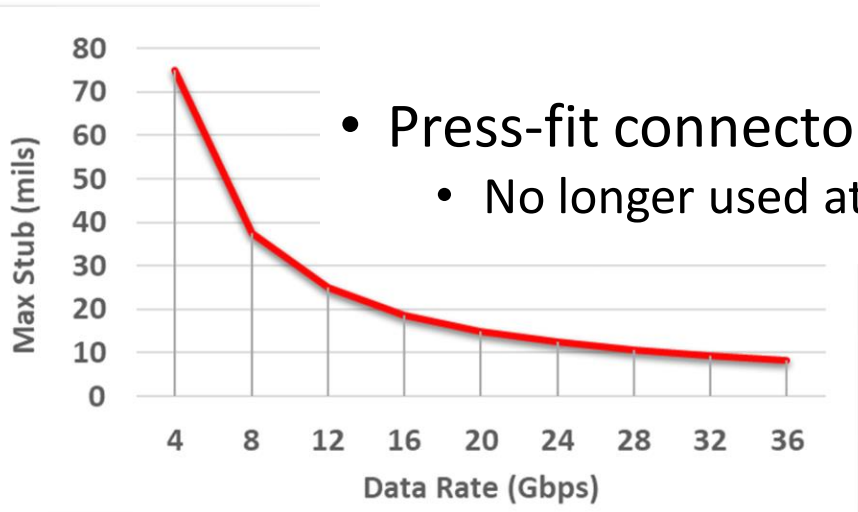
KEYWORDS DISCONTINUITIES INTERCONNECT STRUCTURES SERIAL LINKS SIGNAL INTEGRITY IN PRACTICE

Volts (mV)

Discontinuity Length (mils)


Must remove ALL stubs

- Backdrill vias
 - Gen3/4 failures
- Remove stubs at solder pads
 - Gen5 failures
- Minimize stubs at edge fingers
 - Should be handled by standard
- Press-fit connectors are messy
 - No longer used at higher speeds



Loss

- Can vary 4x in 12" of trace
 - Depending on construction (Lt/Df and Twidth, primarily)
- For many Gens, we've reduced loss by using newer materials
 - But this may be changing
- Step 2 in the "7 Steps" series
- EQ mainly handles loss




Signal Integrity Power Integrity EMC/EMI

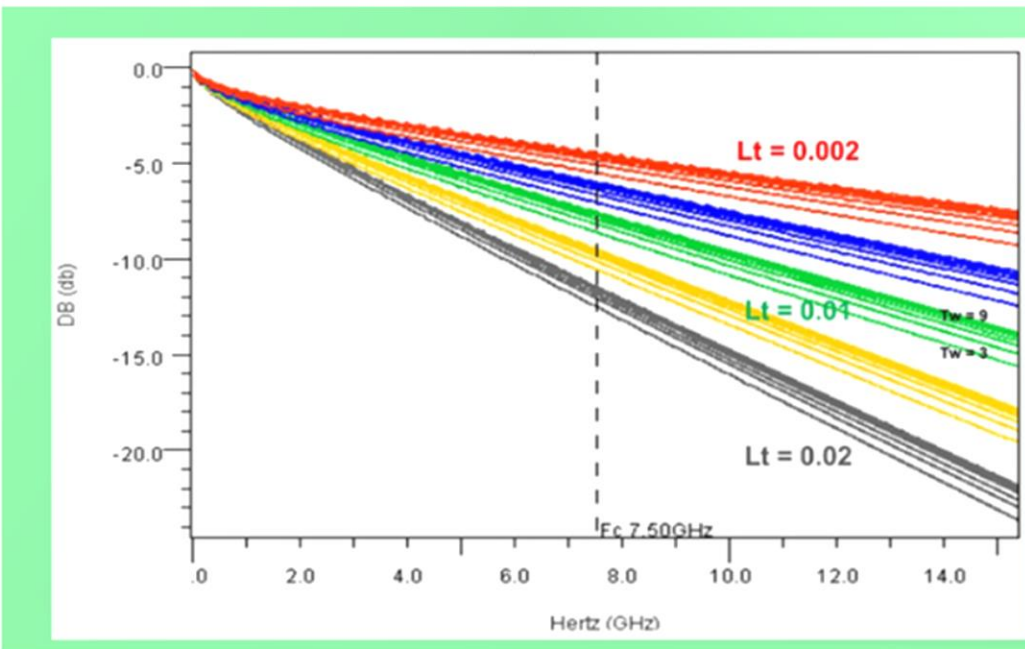
SIGNAL INTEGRITY

7 Steps to Successful Serial Links

July 12, 2022 [Donald Telian](#) [No Comments](#)



KEYWORDS DISCONTINUITIES IMPEDANCE LOSS SERIAL LINKS



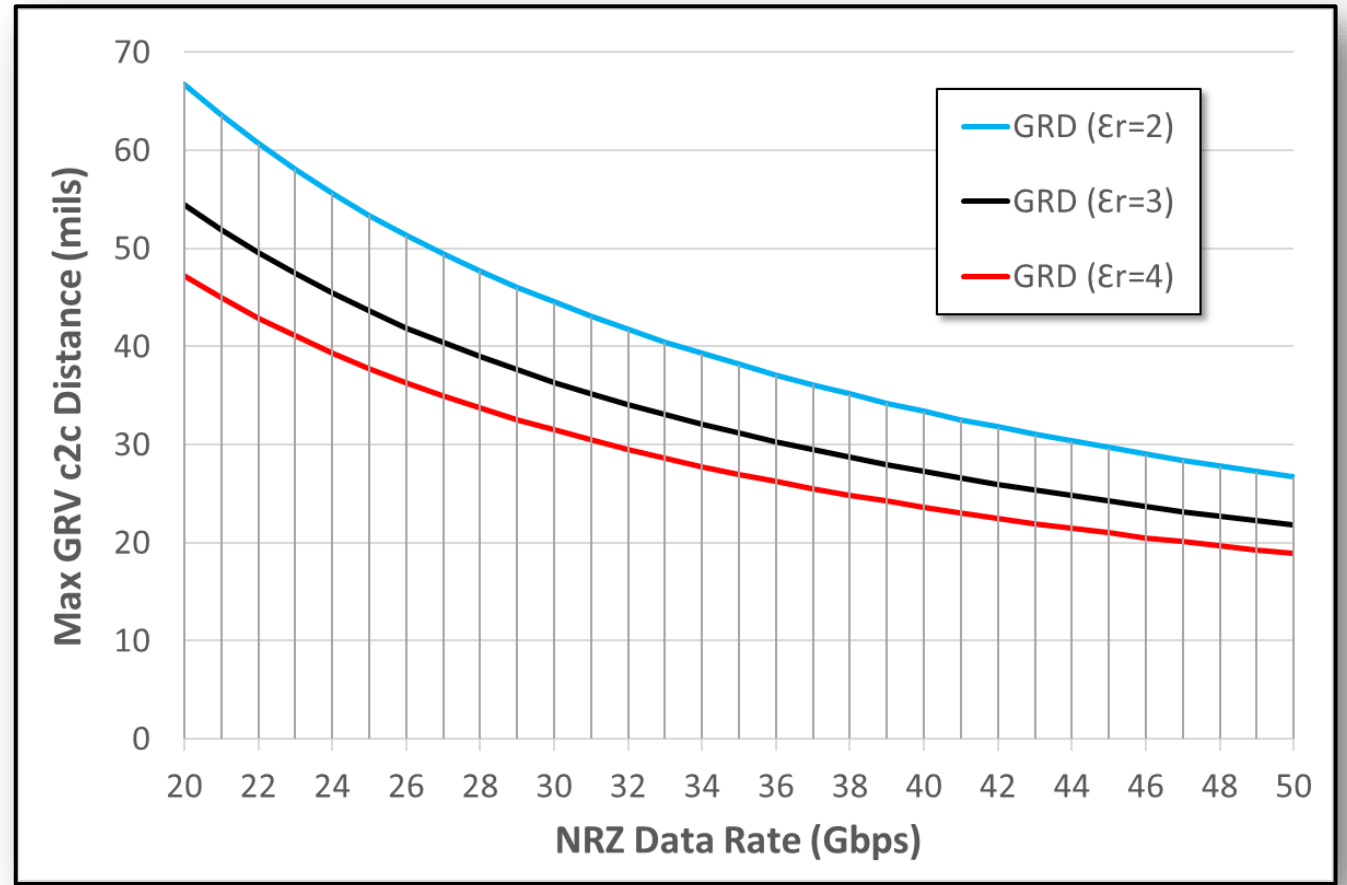
The graph plots Loss in dB (y-axis, from 0.0 to -20.0) against Frequency in Hertz (GHz) (x-axis, from 0 to 14.0). A vertical dashed line indicates the corner frequency $F_c = 7.50\text{GHz}$. Three sets of curves are shown for different trace lengths L_t and widths T_w :

- $L_t = 0.002$ (Red curves)
- $L_t = 0.01$ (Green curves)
- $L_t = 0.02$ (Black curves)

Within each L_t group, there are two curves for $T_w = 9$ and $T_w = 3$. The loss is highest for the largest L_t and T_w values and lowest for the smallest values.

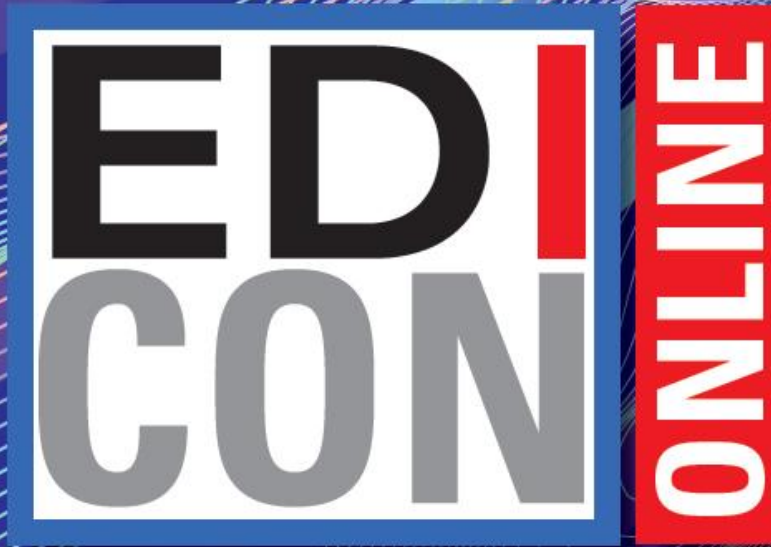
Ground Return Vias (GRVs)

- Gap-Rate Distance (GRD)
 - Signal to GRV distance
 - Center-to-center maximum
 - Based on data rate
- DesignCon 2022 Best Paper:
 - “Proper Ground Return Via Placement for 40+ Gbps Signaling”
- Will be at Signal Integrity Journal soon



In Summary

- Signal Integrity, in practice, has changed/simplified
- Some basic skill necessary to succeed with mainstream SI
 - Captured in the “7 Steps” and “Cheat Sheet”
- Use data rate to make good design decisions
 - Determine what works, and where to focus effort
- As data rates increase:
 - Smaller features become relevant
 - More “stubs” must be managed
 - Loss becomes harder to remove
 - GRVs must move closer



Thank You for Attending

Questions?